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2003/06/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10092890	FILING DATE 03/06/2002	CLASS 257	SUBCLASS 455	GAU 2003 2003	EXAMINER V. YEVSIKOV
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**APPLICANTS: Lutz Markus;

**CONTINUING DATA VERIFIED:

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** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 35 USC 119 conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 11403/13
Verified and Acknowledged Examiners's initials		
TITLE : Si wafer-cap,wafer bonding method using local laser energy, device produced by the method, and system used in the method		
U.S.DEP.T. OF COMM./PAT. & TM-PTO-438L(Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
TERMINAL		Primary Examiner		Application Examiner
DISCLAIMER		PREPARED FOR ISSUE		
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